



Title of Change:	Final Notification of the Transfer to ASE-SH (Shanghai) Assembly of the 32 Lead of Low Profile Quad Flat Package (LQFP).
Proposed first ship date:	24 November 2016
Contact information:	Contact your local ON Semiconductor Sales Office or <Eric.Rupnow@onsemi.com>
Samples:	Contact your local ON Semiconductor Sales Office
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <Andy.Esteva@onsemi.com>
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 12 months prior to implementation of the change. ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <PCN.Support@onsemi.com>.
Change Part Identification:	Products built in ASE-SH will have datecode marking ASWLYYWW while products built in Unisem will have datecode 5WLYYWW
Change category:	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____
Change Sub-Category(s):	<input checked="" type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____
Sites Affected:	<input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input type="checkbox"/> ON Semiconductor site(s) : <input checked="" type="checkbox"/> External Foundry/Subcon site(s) Unisem Batam – ON ASE Assembly & Test (Shanghai)
Description and Purpose:	<p>This is the Final Product Change Notice to make customers aware that ASE-SH, located in Shanghai, China is being qualified as the assembly source for ON Semiconductor's 32 pin LQFP packages. The devices listed on this FPCN have historically been assembled at the Unisem located in Batam, Indonesia. These products which were previously rated as MSL3 have been qualified as MSL2.</p> <p>Upon expiration of the Final PCN, products listed in this PCN will be assembled in ASE-SH.</p>



Reliability Data Summary:

QV DEVICE NAME: NCV7517BFTR2G
 PACKAGE: LQFP 32

Test	Specification	Condition	Interval	Results
HTOL	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs	0/240
HTSL	JESD22-A103	Ta=150°C	1008 hrs	0/80
TC	JESD22-A104	Ta= -65°C to +150°C	500 cyc	0/240
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/239
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/240
PC	J-STD-020 JESD-A113	MSL 2 @ 260 °C		0/720
SD	JSTD002	Ta = 245C, 10 sec		0/ 45

To access file attachments on pdf copy of PCN, please be guided by the steps below:

1. Download pdf copy of the PCN to your computer
2. Open the downloaded pdf copy of the PCN
3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field
4. Then click on the attached file/s

Electrical Characteristic Summary:

Device parameters will continue to meet all Datasheet specifications and reliability will meet or exceed ON Semiconductor established standards.

List of Affected Standard Parts:

Part Number	Qualification Vehicle
NCV7513BFTR2G	NCV7517BFTR2G
NCV7517BFTR2G	NCV7517BFTR2G